

# Highlights of Ebara Products in 2008

## Semiconductor related instruments & devices

### New type bevel polishing system EAC300bi-hp

The bevel polishing process on the edge of the semiconductor wafer is introduced into semiconductor manufacture. This process is based on new technologies to reduce defects and the number of foreign materials from bevel area for improvement the yield in device wafer.

We have developed a new type bevel polishing system to get high performance what provides high throughput and low cost of consumable. And also, this system is reduced footprint as well as various process methods through the compact multiple heads and high speed wafer transfer mechanism (**Photo 28**).

Features:

- (1) High throughput (3.3 times compared with previous model)
- (2) Low cost of consumable (1/3 or less from previous model on standard process)
- (3) Small footprint (16% less from previous model)
- (4) Maximum 8 polishing heads in system (4 heads/module)
- (5) Near edge process application (option)
- (6) IPA (isopropyl alcohol) drying/cleaning module for hydrophobic surface application (option)



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写真28 EAC300bi-hp外観

Photo 28 Outside view of EAC300bi-hp